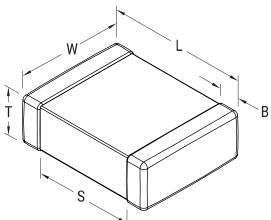


## C1206C102MDRACTU

Aliases (C1206C102MDRAC7800) SMD Comm X7R HV, Ceramic, 1,000 pF, 20%, 1,000 VDC, X7R, SMD, MLCC, High Voltage, Temperature Stable, 1206, 1.5 mm



Click here for the 3D model.

	General Information		
	Series	SMD Comm X7R HV	
	Style	SMD Chip	
	Description	SMD, MLCC, High Voltage, Temperature Stable	
	Features	High Voltage	
	RoHS	Yes	
	Termination	Tin	
	Marking	No	
	AEC-Q200	No	
	Typical Component Weight	25 mg	
	Shelf Life	78 Weeks	
	MCI	1	

		Specifications	
	1206	Capacitance	1,000 pF
	3.2mm +/-0.2mm	Measurement Condition	1 kHz 1.0Vrms
	1.6mm +/-0.2mm	Tolerance	20%
	1mm +/-0.10mm	Voltage DC	1000 VDC
	1.5mm MIN	Dielectric Withstanding Voltage	1,200 VDC
	0.5mm +/-0.25mm	Temperature Range	-55/+125°C
		Temp. Coefficient	X7R
ons			15%, 1kHz 1.0Vrms
	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	
	2500	Dissipation Factor	2 5% 1kHz 10\/rmc

	Marking	No
	AEC-Q200	No
	Typical Component Weight	25 mg
	Shelf Life	78 Weeks
	MSL	1
	Specifications	
	Capacitance	1,000 pF
mm		
	Measurement Condition	1 kHz 1.0Vrms
mm	Measurement Condition Tolerance	1 kHz 1.0Vrms 20%

Dissipation Factor	2.5%1kHz1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Dimensions Chip Size

Packaging Specificatio

Packaging Quantity

L W Т s

В

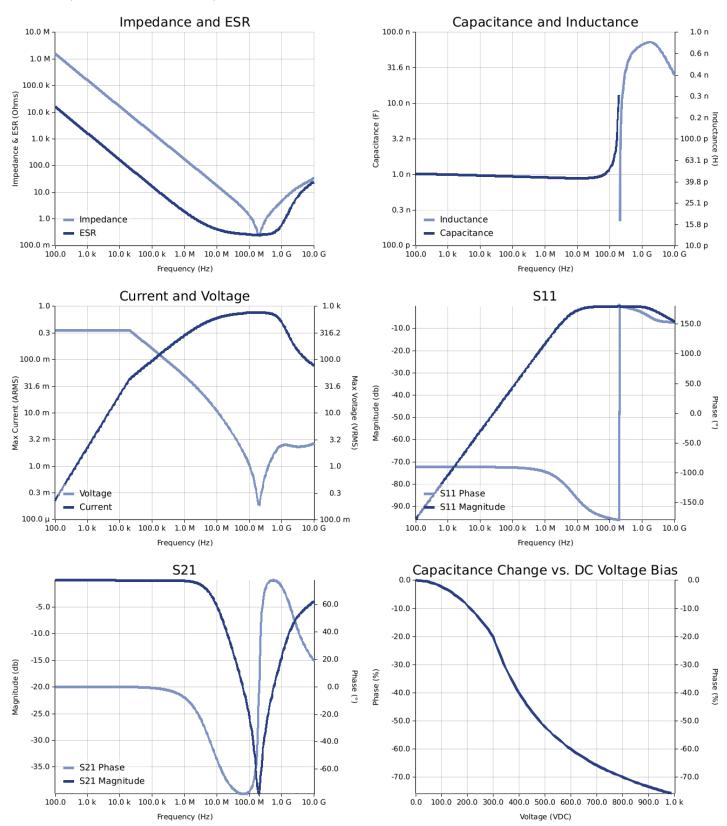
Packaging



C1206C102MDRACTU Aliases (C1206C102MDRAC7800) SMD Comm X7R HV, Ceramic, 1,000 pF, 20%, 1,000 VDC, X7R, SMD, MLCC, High Voltage, Temperature Stable, 1206, 1.5 mm

## Simulations

For the complete simulation environment please visit K-SIM.

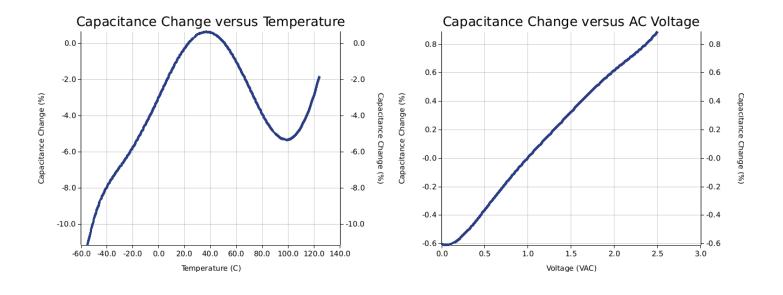


Generated 07/10/2025



C1206C102MDRACTU Aliases (C1206C102MDRAC7800)

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## C1206C102MDRACTU

Aliases (C1206C102MDRAC7800) SMD Comm X7R HV, Ceramic, 1,000 pF, 20%, 1,000 VDC, X7R, SMD, MLCC, High Voltage, Temperature Stable, 1206, 1.5 mm

## These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.